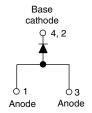
# VS-8EWS..SPbF High Voltage Series

Vishay Semiconductors

## **High Voltage Surface Mount** Input Rectifier Diode, 8 A

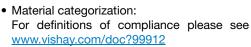




PRODUCT SUMMARY					
Package	D-PAK (TO-252AA)				
I <sub>F(AV)</sub>	8 A				
$V_{R}$	800 V, 1200 V				
V <sub>F</sub> at I <sub>F</sub>	1.1 V				
I <sub>FSM</sub>	150 A				
T <sub>J</sub> max.	150 °C				
Diode variation	Single die				

#### **FEATURES**

• Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C







### **APPLICATIONS**

- Input rectification
- · Vishay Semiconductors switches and output rectifiers which are available in identical package outlines

#### **DESCRIPTION**

The 8EWS..SPbF rectifier High Voltage Series has been optimized for very low forward voltage drop, with moderate leakage. The glass passivation technology used has reliable operation up to 150 °C junction temperature.

The high reverse voltage range available allows design of input stage primary rectification with outstanding voltage surge capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS								
APPLICATIONS	SINGLE-PHASE BRIDGE	THREE-PHASE BRIDGE	UNITS					
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 µm) copper	1.2	1.6						
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	Α					
Aluminum IMS with heatsink, R <sub>thCA</sub> = 5 °C/W	5.5	6.5						

• T<sub>A</sub> = 55 °C, T<sub>J</sub> = 125 °C, footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	CHARACTERISTICS	VALUES	UNITS					
I <sub>F(AV)</sub>	Sinusoidal waveform at T <sub>C</sub> = 116 °C	8	A					
$V_{RRM}$		800/1200	V					
I <sub>FSM</sub>		150	A					
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V					
TJ		- 55 to 150	°C					

VOLTAGE RATINGS								
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA					
8EWS08SPbF	800	900	0.5					
8EWS12SPbF	1200	1300	0.5					



# **VS-8EWS..SPbF High Voltage Series**

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ABSOLUTE MAXIMUM RATINGS							
PARAMETER	VALUES	UNITS					
Maximum average forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 105 °C, 180° conduction half sine wave	8				
Maximum peak one cycle		10 ms sine pulse, rated V <sub>RRM</sub> applied	125	Α			
non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, no voltage reapplied	150				
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s			
Maximum I-t for fusing	1-1	10 ms sine pulse, no voltage reapplied	110				
Maximum $I^2\sqrt{t}$ for fusing $I^2\sqrt{t}$ $t=0.1$ ms to 10 ms, no voltage re		t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s			

ELECTRICAL SPECIFICATIONS								
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS							
Maximum forward voltage drop	$V_{FM}$	8 A, T <sub>J</sub> = 25 °C	1.1	V				
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C	T 450 00		mΩ			
Threshold voltage	V <sub>F(TO)</sub>	1j = 130 C	0.82	V				
Maximum roveree leekege gurrent	I <sub>RM</sub>	T <sub>J</sub> = 25 °C	V - Batad V	0.05	- mA			
Maximum reverse leakage current		T <sub>J</sub> = 150 °C	V <sub>R</sub> = Rated V <sub>RRM</sub>	0.50				

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		- 55 to 150	°C			
Soldering temperature T <sub>S</sub>			260				
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W			
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA (1)</sub>		62	C/VV			
Approximate weight			1	g			
Approximate weight			0.03	OZ.			
Marking device		Case style D-PAK (TO-252AA)	8EWS12S				

### Note

<sup>(1)</sup> When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 µm) copper 40 °C/W For recommended footprint and soldering techniques refer to application note #AN-994

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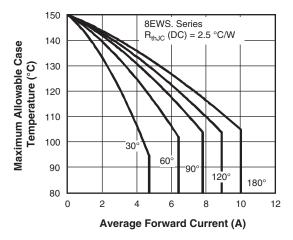


Fig. 1 - Current Rating Characteristics

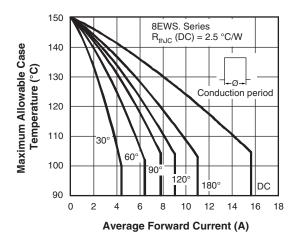


Fig. 2 - Current Rating Characteristics

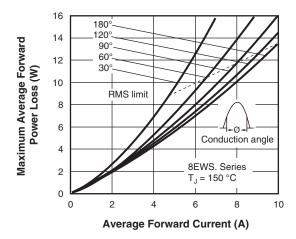


Fig. 3 - Forward Power Loss Characteristics

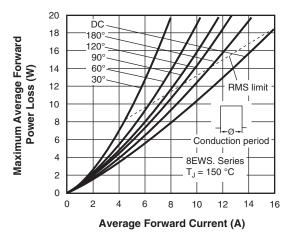


Fig. 4 - Forward Power Loss Characteristics

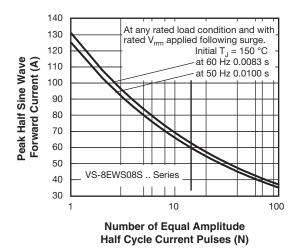


Fig. 5 - Maximum Non-Repetitive Surge Current

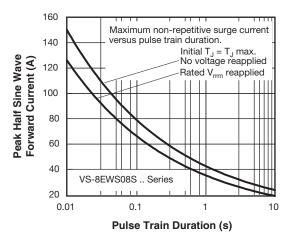


Fig. 6 - Maximum Non-Repetitive Surge Current

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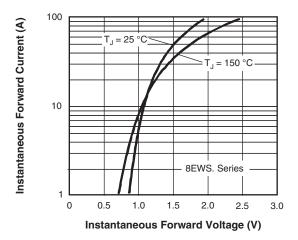


Fig. 7 - Forward Voltage Drop Characteristics

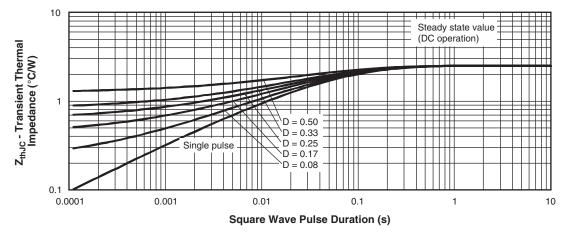


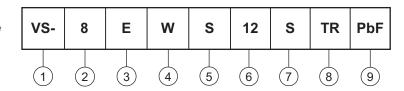
Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristics

## **VS-8EWS..SPbF High Voltage Series**

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#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

3 - Circuit configuration:

E = Single diode

4 - Package:

8

W = D-PAK

5 - Type of silicon:

S = Standard recovery rectifier

08 = 800 V

6 - Voltage ratings -

12 = 1200 V

7 - S = Surface mountable

TR = Tape and reel

• TRR = Tape and reel (right oriented)

• TRL = Tape and reel (left oriented)

9 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS						
Dimensions <u>www.vishay.com/doc?95016</u>						
Part marking information	www.vishay.com/doc?95059					
Packaging information	www.vishay.com/doc?95033					



## Vishay Semiconductors

**NOTES** 

3

2

MAX.

0.410

0.070

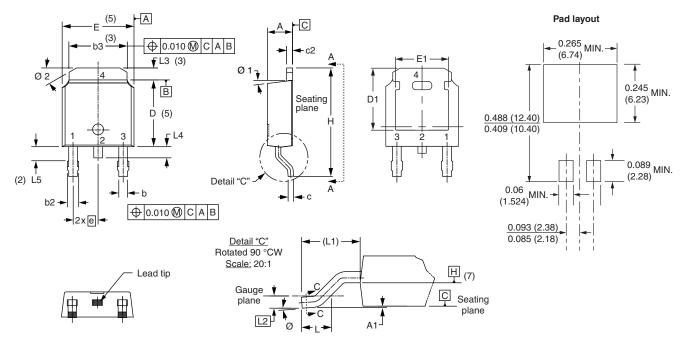
0.050

0.040

0.060

# **D-PAK (TO-252AA)**

#### **DIMENSIONS** in millimeters and inches



Ī	SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES			
		MIN.	MAX.	MIN.	MAX.	NOTES		STIMBUL	MIN.	MAX.	MIN.	MAX	
ſ	Α	2.18	2.39	0.086	0.094			е	2.29	BSC	0.090	BSC	
ſ	A1	-	0.13		0.005			Н	9.40	10.41	0.370	0.41	
Ī	b	0.64	0.89	0.025	0.035			L	1.40	1.78	0.055	0.07	
Ī	b2	0.76	1.14	0.030	0.045			L1	2.74	BSC	0.108	REF.	
ſ	b3	4.95	5.46	0.195	0.215	3		L2	0.51	BSC	0.020	BSC	
Ī	С	0.46	0.61	0.018	0.024			L3	0.89	1.27	0.035	0.05	
Ī	c2	0.46	0.89	0.018	0.035			L4	-	1.02	-	0.04	
ſ	D	5.97	6.22	0.235	0.245	5		L5	1.14	1.52	0.045	0.06	
Ī	D1	5.21	-	0.205	-	3		Ø	0°	10°	0°	10°	
ſ	Е	6.35	6.73	0.250	0.265	5		Ø1	0°	15°	0°	15°	
Ī	E1	4.32	-	0.170	-	3		Ø2	25°	35°	25°	35°	

### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- Lead dimension uncontrolled in L5
- Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- Outline conforms to JEDEC outline TO-252AA



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